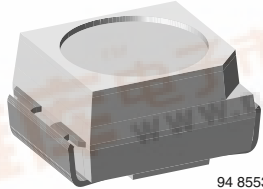




VEMT3700

Vishay Semiconductors

Silicon NPN Phototransistor, RoHS Compliant



FEATURES

- Package type: surface mount
- Package form: PLCC-2
- Dimensions (L x W x H in mm): 3.5 x 2.8 x 1.75
- High photo sensitivity
- High radiant sensitivity
- Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\varphi = \pm 60^\circ$
- Package notch indicates collector
- Package matched with IR emitter series VSML3710
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Lead (Pb)-free reflow soldering
- Lead (Pb)-free component in accordance with RoHS 2002/95/EC and WEEE 2002/96/EC



RoHS COMPLIANT

DESCRIPTION

VEMT3700 is a high speed silicon NPN epitaxial planar phototransistor in a miniature PLCC-2 package for surface mounting on printed boards. The device is sensitive to visible and near infrared radiation.

APPLICATIONS

- Photo interrupters
- Miniature switches
- Counters
- Encoders
- Position sensors
- Light sensors

PRODUCT SUMMARY			
COMPONENT	I _{ca} (mA)	φ (deg)	$\lambda_{0.1}$ (nm)
VEMT3700	0.5	± 60	450 to 1080

Note

Test conditions see table "Basic Characteristics"

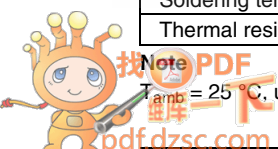
ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VEMT3700-GS08	Tape and reel	MOQ: 7500 pcs, 1500 pcs/reel	PLCC-2
VEMT3700-GS18	Tape and reel	MOQ: 8000 pcs, 8000 pcs/reel	PLCC-2

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Collector emitter voltage		V _{CEO}	70	V
Emitter collector voltage		V _{ECO}	5	V
Collector current		I _C	50	mA
Collector peak current	t _p /T ≤ 0.1, t _p ≤ 10 μs	I _{CM}	100	mA
Power dissipation		P _V	100	mW
Junction temperature		T _J	100	°C
Operating temperature range		T _{amb}	- 40 to + 100	°C
Storage temperature range		T _{stg}	- 40 to + 100	°C
Soldering temperature	Acc. reflow solder profile fig. 10	T _{sd}	260	°C
Thermal resistance junction/ambient	Soldered on PCB with pad dimensions: 4 mm x 4 mm	R _{thJA}	400	K/W

Note: T_{amb} = 25 °C, unless otherwise specified



VENT3700

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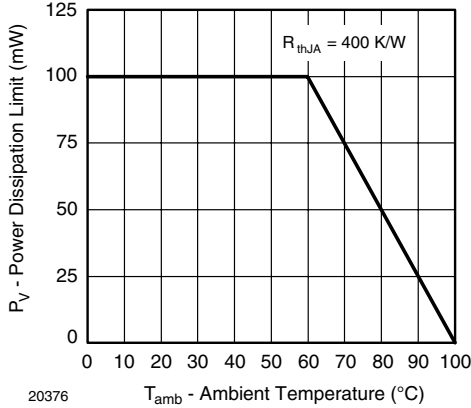


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

BASIC CHARACTERISTICS						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Collector emitter breakdown voltage	I _C = 1 mA	V _{(BR)CEO}	70			V
Collector emitter dark current	V _{CE} = 20 V, E = 0	I _{CEO}		1	200	nA
Collector emitter capacitance	V _{CE} = 5 V, f = 1 MHz, E = 0	C _{CEO}		3		pF
Collector lighth current	E _e = 1 mW/cm ² , λ = 950 nm, V _{CE} = 5 V	I _{ca}	0.25	0.5		mA
Angle of half sensitivity		φ		± 60		deg
Wavelength of peak sensitivity		λ _p		850		nm
Range of spectral bandwidth		λ _{0.1}		450 to 1080		nm
Collector emitter saturation voltage	E _e = 1 mW/cm ² , λ = 950 nm, I _C = 0.1 mA	V _{CEsat}		0.15	0.3	V
Rise time, fall time	V _S = 5 V, I _C = 1 mA, λ = 950 nm, R _L = 1 kΩ	t _r /t _f		6		μs
	V _S = 5 V, I _C = 1 mA, λ = 950 nm, R _L = 100 Ω	t _r /t _f		2		μs
Cut-off frequency	V _S = 5 V, I _C = 2 mA, R _L = 100 Ω	f _c		180		kHz

Note

T_{amb} = 25 °C, unless otherwise specified

BASIC CHARACTERISTICS

T_{amb} = 25 °C, unless otherwise specified

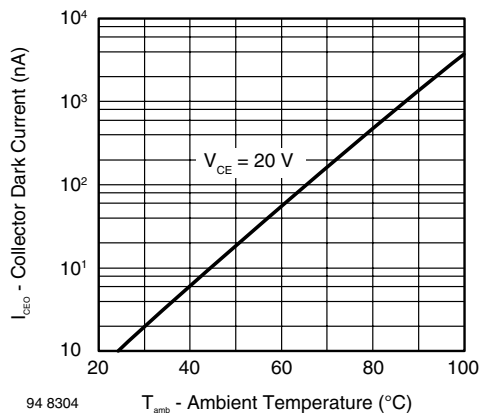


Fig. 2 - Collector Dark Current vs. Ambient Temperature

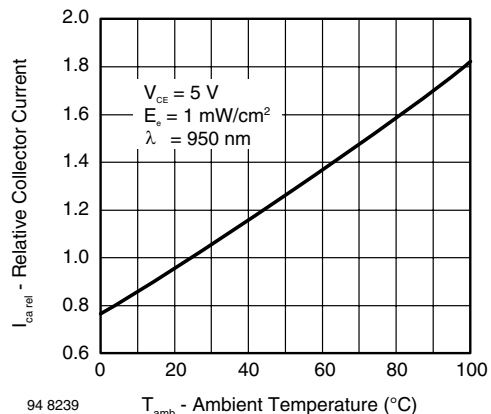
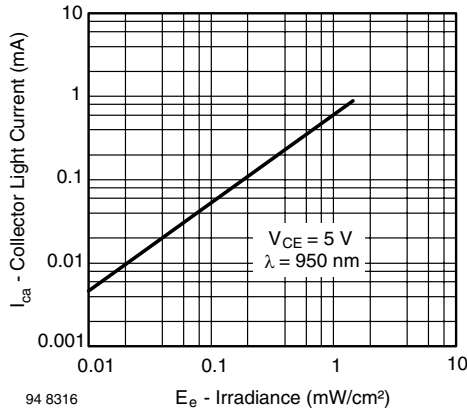
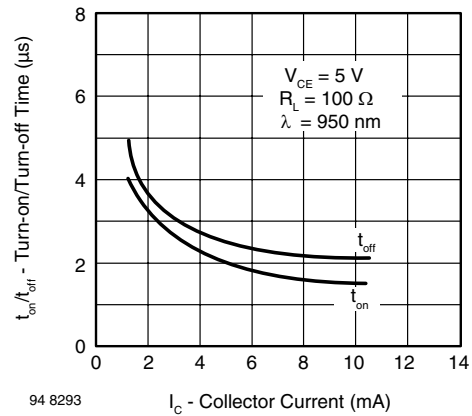


Fig. 3 - Relative Collector Current vs. Ambient Temperature



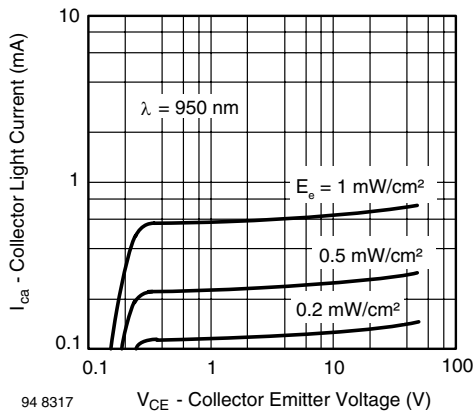
94 8316 E_e - Irradiance (mW/cm^2)

Fig. 4 - Collector Light Current vs. Irradiance



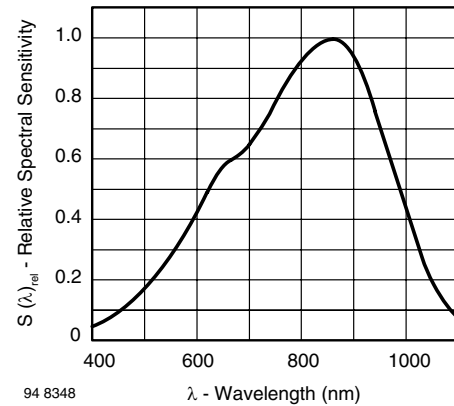
94 8293 I_c - Collector Current (mA)

Fig. 7 - Turn-on/Turn-off Time vs. Collector Current



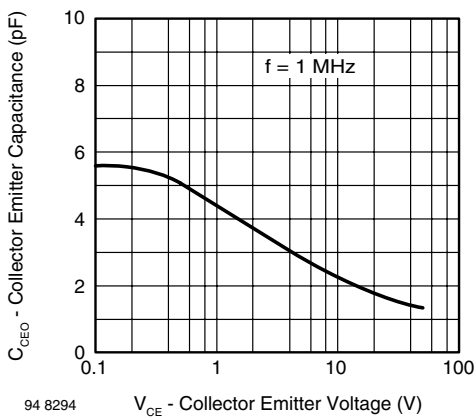
94 8317 V_{CE} - Collector Emitter Voltage (V)

Fig. 5 - Collector Light Current vs. Collector Emitter Voltage



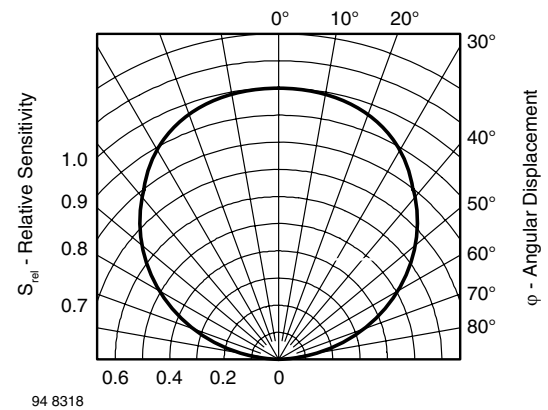
94 8348 λ - Wavelength (nm)

Fig. 8 - Relative Spectral Sensitivity vs. Wavelength



94 8294 V_{CE} - Collector Emitter Voltage (V)

Fig. 6 - Collector Emitter Capacitance vs. Collector Emitter Voltage



94 8318

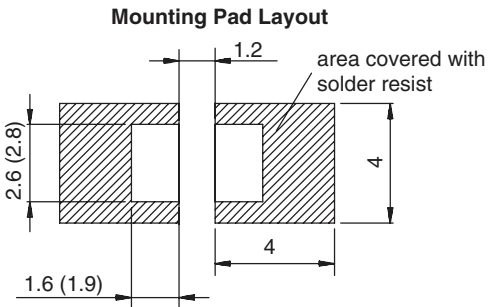
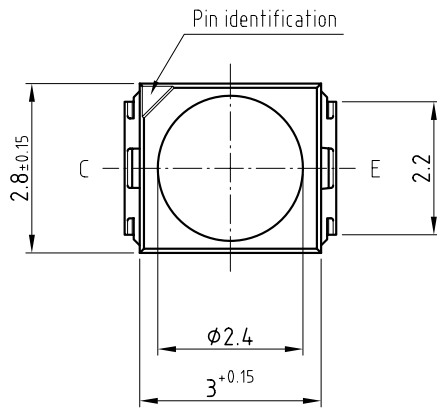
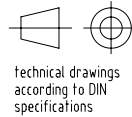
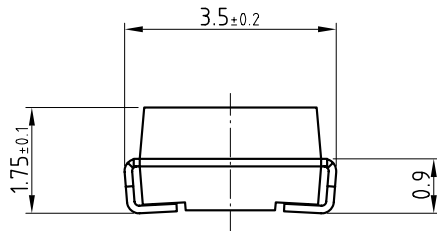
Fig. 9 - Relative Radiant Sensitivity vs. Angular Displacement

VENT3700

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PACKAGE DIMENSIONS in millimeters



Drawing-No.: 6.541-5067.03-4
 Issue: 1; 30.05.07
 20873

SOLDER PROFILE

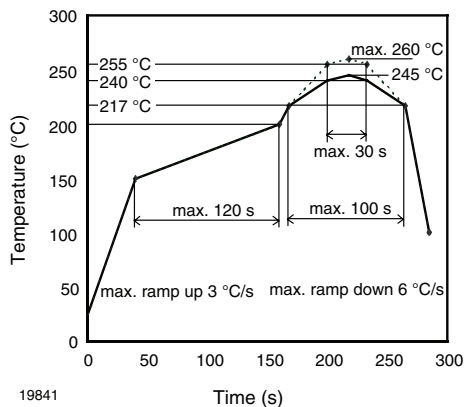


Fig. 10 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020D

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:

Floor life: 4 weeks

Conditions: $T_{amb} < 30\text{ °C}$, $RH < 60\%$

Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label. Devices taped on reel dry using recommended conditions 192 h at $40\text{ °C} (+5\text{ °C})$, $RH < 5\%$.



TAPE AND REEL

PLCC-2 components are packed in antistatic blister tape (DIN IEC (CO) 564) for automatic component insertion. Cavities of blister tape are covered with adhesive tape.

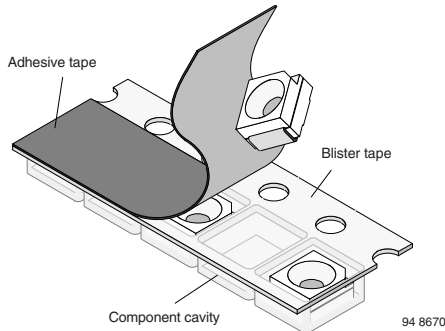


Fig. 11 - Blister Tape

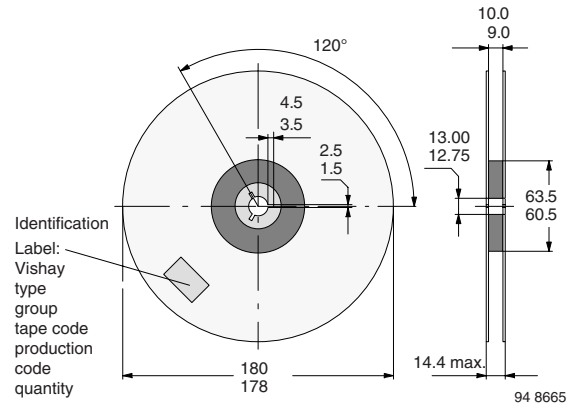


Fig. 14 - Dimensions of Reel-GS08

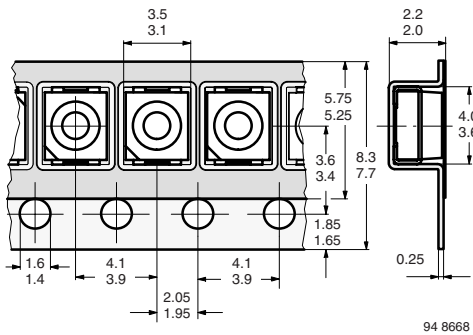


Fig. 12 - Tape Dimensions in mm for PLCC-2

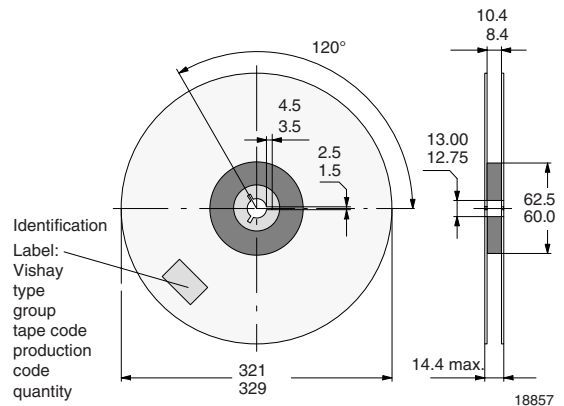


Fig. 15 - Dimensions of Reel-GS18

MISSING DEVICES

A maximum of 0.5 % of the total number of components per reel may be missing, exclusively missing components at the beginning and at the end of the reel. A maximum of three consecutive components may be missing, provided this gap is followed by six consecutive components.

COVER TAPE REMOVAL FORCE

The removal force lies between 0.1 N and 1.0 N at a removal speed of 5 mm/s. In order to prevent components from popping out of the blisters, the cover tape must be pulled off at an angle of 180° with regard to the feed direction.

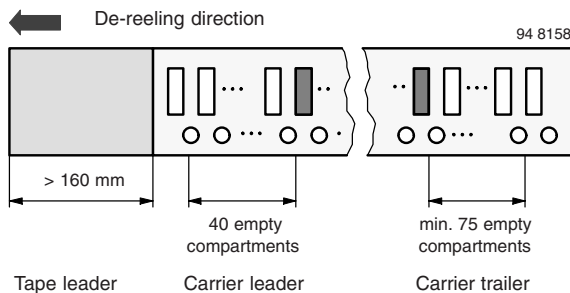


Fig. 13 - Beginning and End of Reel

The tape leader is at least 160 mm and is followed by a carrier tape leader with at least 40 empty compartments. The tape leader may include the carrier tape as long as the cover tape is not connected to the carrier tape. The least component is followed by a carrier tape trailer with a least 75 empty compartments and sealed with cover tape.



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All product specifications and data are subject to change without notice.

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